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2 [Optimizations for a highly cost-efficient programmable logic architecture](#)

Kerry Veenstra, Bruce Pedersen, Jay Schleicher, Chiakang Sung

 March 1998 **Proceedings of the 1998 ACM/SIGDA sixth international symposium on Field programmable gate arrays**

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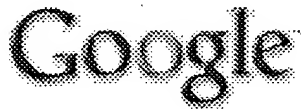
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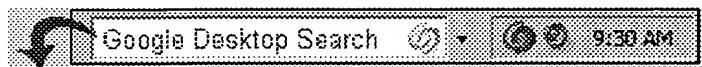
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